



**CLEAN VERSION OF AMENDED SPECIFICATION PARAGRAPHS**

**METHOD OF FORMING AN OPTICAL FIBER INTERCONNECT THROUGH A  
SEMICONDUCTOR WAFER**

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**Paragraph 1 on page 1:**

This application is a Continuation of U.S. application, Serial No. 09/031,975, filed on February 26, 1998, now U.S. Patent No. 6,150,188.